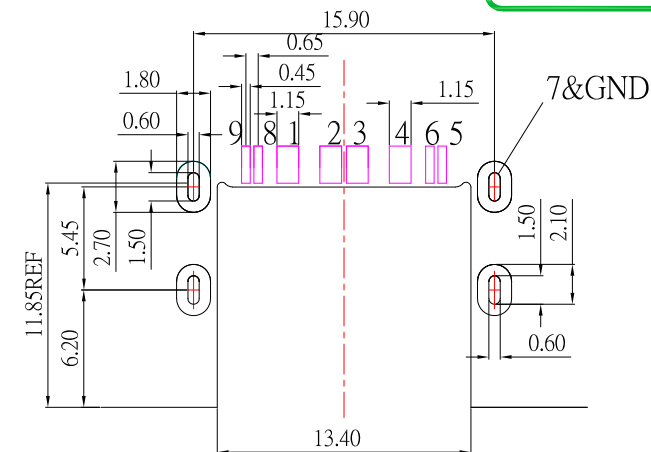
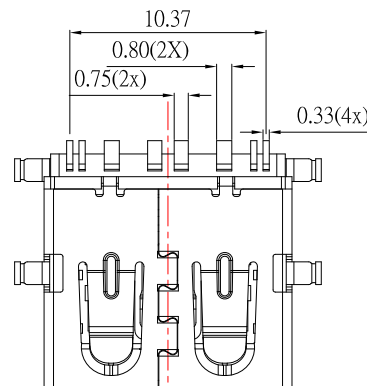
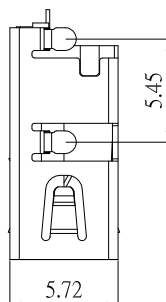
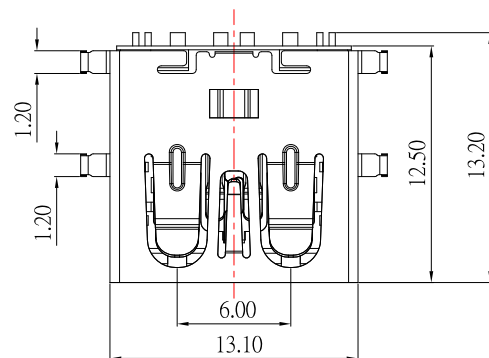
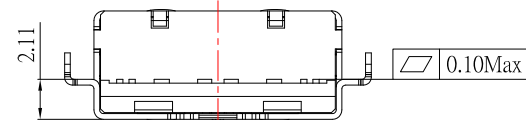




SUA-110M9-32x-S277

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LAYOUT

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

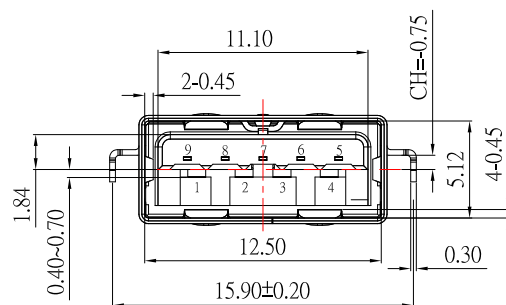
- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 3.0 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Mating Force: 8N~20N
- 3.6 Unmating Force: 8N~20N
- 3.7 Operation Temperature: -25°C ~ +85°C

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



广东科斯达电子科技有限公司
GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 11/02/23
DATE: 11/02/23
DATE: 11/02/23

MAT'L
FINISH
SCALE: 1 : 1
SHEET NO. 1 of 1

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
USB 3.1 10G AF SMT本體長=12.5mm, 板上高2.11 無捲邊
SUA-110M9-32x-S277
SUA-110M9-32x-S277

SIZE: A4
VER: R

ITEM NO. DESCRIPTION DRAWN DATE